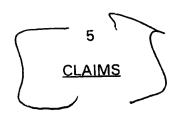
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## What is claimed is:

- 1 1. An apparatus for removing an edge bead of a coating of material that has been spun onto the surface of a semiconductor wafer, the apparatus comprising:
- been spun onto the surface of a semiconductor water, the apparatus comprising.

  a. neans for dispensing a solvent selectively onto the edge of the wafer;
- 4 and
- b. means surrounding the dispensing means for vacuuming excess
- 6 solvent and dissolved coating material from the edge of the wafer.
- 1 2. An apparatus according to Claim 1, wherein the dispensing means is a nozzle and the vacuuming means comprises a vacuum port surrounding the nozzle.
- 1 3. An apparatus according to Claim 1, further comprising:
  - a. means for spinning the semiconductor wafer; and
  - b. means for applying a coating material to the spinning wafer.
- 1 4. A method for removing an edge bead of a coating of material that has been
- 2 spun onto the surface of a semiconductor wafer, the method comprising the steps
- 3 of:
- 4 a. dispensing a solvent selectively onto the edge of the wafer to dissolve
- 5 the coating material at the extreme edge of the wafer; and
- 6 b. applying a suction to vacuum excess solvent and dissolved coating
- 7 material from the edge of the wafer
- 1 5. A method according to Claim 4 wherein the suction is applied to an area
- 2 immediately surrounding a location at which the solvent is dispensed onto the
- 3 wafer.

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- 1 6. A method according to Claim 4, wherein the step of vacuuming is performed substantially simultaneously with the step of dispensing.
- 1 7. A method for spin coating a semiconductor wafer with a soluble material,
- 2 comprising the steps of:
  - a. spinning the semiconductor wafer;
- b. applying a coating material to the spinning wafer;
- 5 c. dispensing a solvent selectively onto the edge of the wafer to dissolve
- 6 the coating material at the extreme edge of the wafer; and
  - d. applying a suction to the edge of the wafer to vacuum excess solvent and dissolved coating material from the edge of the wafer.
- 1 8. A method according to aim 7 wherein the suction is applied to an area
- 2 immediately surrounding a location at which the solvent is dispensed onto the
- 3 wafer.
- 1 9. A method according to Claim 7, wherein the step of dispensing the solvent
- 2 is performed substantially simultaneously with the step of applying a suction.
- 1 10. A method for dispensing a chemical onto a semiconductor wafer, comprising
- 2 the steps of:
- a. dispensing the chemical selectively onto the wafer; and
- b. applying a suction to an area\immediately surrounding a location at
- 5 which the chemical is dispensed onto the wafer.
- 1 11. A method according to Claim 10, wherein the suction is applied substantially
- 2 simultaneously with the dispensing of the chemical.